

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-17. (Canceled)

18. (Original) An apparatus for manufacturing a semiconductor device, comprising:
a stage to hold a semiconductor wafer during processing;
an exposure slit positioned relative to the stage;
projection optics to focus a light beam through the exposure slit and onto a selected portion of the semiconductor wafer;
at least one vacuum tube adjacent the exposure slit; and
a single opening formed in the vacuum tube at a selected location to cause air flow in the exposure slit away from a lens of the projection optics.
19. (Original) The apparatus of claim 18, wherein the selected location of the single opening is at about a mid-point of the exposure slit.
20. (Original) The apparatus of claim 18, wherein the single opening has a predetermined size and shape.
21. (Original) The apparatus of claim 18, further comprising
a second vacuum tube adjacent the exposure slit on an opposite side of the exposure slit from the at least one vacuum tube; and
a single opening formed in the second vacuum tube at a selected location.
22. (Original) The apparatus of claim 21, wherein the selected location of each single opening is at about a mid-point of the exposure slit.
23. (Original) The apparatus of claim 21, wherein the selected location of the single openings causes a maximum reduction of outgassed particles from contaminating the lens.
24. (Original) A method of making a vacuum debris removal system, comprising:
providing at least one vacuum tube; and

PRELIMINARY AMENDMENT

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Title: VACUUM DEBRIS REMOVAL SYSTEM FOR AN INTEGRATED CIRCUIT MANUFACTURING DEVICE

Assignee: Intel Corporation

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forming a single opening in the at least one vacuum tube at a selected location to cause air flow away from an element of an integrated circuit manufacturing device.

25. (Original) The method of claim 24, further comprising forming the single opening to have a predetermined size and shape.

26. (Original) The method of claim 24, further comprising selecting the location to form the single opening to be at about a mid-point of an exposure slit of the integrated circuit manufacturing device.

27. (Original) The method of claim 24, further comprising:
disposing the at least one vacuum tube on one side of an exposure slit of the integrated circuit manufacturing device;
disposing a second vacuum tube on an opposite side of the exposure slit; and
forming a single hole in the second vacuum tube to cause air flow in the exposure slit away from the element of the integrated circuit manufacturing device.

Claims 28-31. (Canceled)